

## PRELIMINARY DATASHEET

# N4000-29

## Advanced Lead-Free, High-Tg Multifunctional Epoxy

*N4000-29 is an advanced, lead-free, low-CTE, high Tg (180° C by DSC) multifunctional epoxy dielectric substrate. This material has been designed for use not only in standard multilayer PWB designs, but for today's toughest, high-performance, lead-free applications.*

### Key Features

#### Low Z-axis expansion

- Reduced expansion improves through-hole reliability
- Excellent for high layer count assemblies
- Designed to withstand multiple reflow excursions and repair operations

#### Tg >180°C, excellent thermal stability and moisture resistance

- Improved lead-free assembly compatibility
- Proven IST testing results
- Exceptional peel strength
- Suitable for high-layer count, sophisticated PWB designs

#### CAF Resistant

- Providing long term reliability in end products

#### Proprietary resin chemistry

- Extremely low Z-CTE.
- Improved thermal stability, CAF and moisture resistance when compared to traditional FR-4

#### Superior electrical properties

- Supporting advanced technology PWB designs

#### Optimized FR-4 processing

- Superior rheology providing consistent controlled flow and superior via topography.
- 75 min press at 185°C and 200-300 psi

#### Available in a variety of constructions

- Vacuum laminated
- Available in a wide variety of constructions, copper weights and glass styles including standard copper, double treat and RTFOIL® laminate.
- All Nelco and Neltec materials are RoHS compliant.



### Applications

- Advanced Lead-Free Assembly Substrate
- Large Format Backplanes
- Tight Tolerance Via to Via Applications
- High I / O Count BGA Substrates
- Extreme Layer Count Multilayers
- Lead-Free DCA Applications
- High Temperature Underhood Automotive
- Telecommunications Infrastructure
- Sophisticated Data Storage Applications

### Global Availability

Contact Nelco or Neltec worldwide:

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### Advanced Lead-Free, High-Tg Multifunctional Epoxy

Property / Condition	Value (U.S. Units)		Value (Metric Units)		Test Method
<b>Mechanical Properties</b>					
Peel Strength - 1 oz. (35 micron) Cu					
After Solder Float	10.1	lb/inch	1.81	N/mm	IPC-TM-650.2.4.8
At Elevated Temperature	8.9	lb/inch	1.56	N/mm	IPC-TM-650.2.4.8.2a
After Exposure to Process Solutions	9.7	lb/inch	1.73	N/mm	IPC-TM-650.2.4.8
X/Y CTE [-40°C to +125°C]	15 - 17	ppm/°C	15 - 17	ppm/°C	IPC-TM-650.2.4.41
Z Axis Expansion [50°C to 260°C]	3.2	%	3.2	%	IPC-TM-650.2.4.41
Young's Modulus (X/Y)	3.6/2.9	psi x 10 <sup>6</sup>	22.6/18.2	GN/m <sup>2</sup>	ASTM D3039
Poisson's Ratios (X/Y)	0.18/0.16		0.18/0.16		ASTM D3039
Thermal Conductivity	0.46	W/mK	0.46	W/mK	ASTM E1461-92
Specific Heat	0.92	J/gK	0.92	J/gK	ASTM E1461-92
<b>Electrical Properties</b>					
Dielectric Constant (50% resin content)					
@ 1 MHz (TFC/LCR Meter)	4.50		4.50		IPC-TM-650.2.5.5.3
@ 10 GHz (Split Post Cavity)	4.15		4.15		Internal Method
@ 10 GHz (Stripline)	3.89		3.89		Internal Method
Dissipation Factor (50% resin content)					
@ 1 MHz (TFC/LCR Meter)	0.016		0.016		IPC-TM-650.2.5.5.3
@ 2.5 GHz ( Split Post Cavity)	0.015		0.015		Internal Method
@ 10 GHz ( Split Post Cavity)	0.017		0.017		Internal Method
Volume Resistivity					
C - 96/35/90	10 <sup>7</sup>	MΩ - cm	10 <sup>7</sup>	MΩ - cm	IPC-TM-650.2.5.17.1
E - 24/125	10 <sup>8</sup>	MΩ - cm	10 <sup>8</sup>	MΩ - cm	IPC-TM-650.2.5.17.1
Surface Resistivity					
C - 96/35/90	10 <sup>6</sup>	MΩ	10 <sup>6</sup>	MΩ	IPC-TM-650.2.5.17.1
E - 24/125	10 <sup>7</sup>	MΩ	10 <sup>7</sup>	MΩ	IPC-TM-650.2.5.17.1
Electric Strength	1100	V/mil	4.2x10 <sup>4</sup>	V/mm	IPC-TM-650.2.5.6.2
Dielectric Breakdown	>50	kV	>50	kV	IPC-TM-650.2.5.6
Arc Resistance	129	seconds	129	seconds	IPC-TM-650.2.5.1
<b>Thermal Properties</b>					
Glass Transition Temperature (T <sub>g</sub> )					
DSC (°C)	180	°C	180	°C	IPC-TM-650.2.4.25c
TMA (°C)	170	°C	170	°C	IPC-TM-650.2.4.24c
Degradation Temp (TGA) (5% wt. loss)	350	°C	350	°C	IPC-TM-650.2.3.40
Pressure Cooker - 60 min then solder dip					IPC-TM-650.2.6.16
@288°C until failure (max 10 min.)	Pass		Pass		(modified)
T <sub>260</sub>	>60	minutes	>60	minutes	IPC-TM-650.2.4.24.1
T <sub>288</sub>	15	minutes	15	minutes	IPC-TM-650.2.4.24.1
<b>Chemical/Physical Properties</b>					
Moisture Absorption	0.15	wt. %	0.15	wt. %	IPC-TM-650.2.6.2.1
Methylene Chloride Resistance	0.01	% wt. chg.	0.01	% wt. chg.	IPC-TM-650.2.3.4.3
Density [50% resin content]	1.99	g/cm <sup>3</sup>	1.99	g/cm <sup>3</sup>	Internal Method

All test data provided are typical values and not intended to be specification values. For review of critical specification tolerances, please contact a Nelco representative directly. Nelco reserves the right to change these typical values as a natural process of refining our testing equipment and techniques.

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\*CAF resistance has been established to greater than 500 hours using a specific OEM coupon design and test procedure. For details on this or other CAF tests, please visit [www.parkedro.com](http://www.parkedro.com).

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